

**Listing of Claims:**

1. (Previously presented) A circuit, comprising:  
a circuit board;  
an electronic component mounted on the circuit board; and  
a heat-conducting structure immediately adjacent to the electronic component and increasing a thermal mass of the electronic component so as to reduce a thermal drift of the electronic component,  
wherein the electronic component controls a frequency of a signal used by the circuit.
2. (Cancelled)
3. (Previously presented) The circuit of claim 1, wherein the structure comprises a metal case around the electronic component.
4. (Previously presented) The circuit of claim 1, wherein the structure comprises a ceramic case around the electronic component.
5. (Cancelled)
6. (Previously presented) The circuit of claim 1, further comprising a thermal insulator that encases the structure.
- 7-11. (Cancelled)
12. (Original) The circuit of claim 1, wherein the circuit is an oscillator circuit.
13. (Original) The circuit of claim 1, wherein the circuit is a clock circuit.
14. (Previously Presented) The circuit of claim 13, further comprising:  
means for communication via a network;  
means for synchronizing a local time value in the clock circuit in response to a set of messages transferred via the network.

15. (Previously presented) A distributed system having a set of nodes, each node comprising:  
a local clock including a crystal component;  
a heat-conducting structure immediately adjacent to the crystal component and increasing a thermal mass of the crystal component so as to reduce a thermal drift of the crystal component.

16. (Cancelled)

17. (Previously presented) The distributed system of claim 15, wherein the structure comprises a metal case around the crystal component.

18. (Previously presented) The distributed system of claim 15, wherein the structure comprises a ceramic case around the crystal component.

19. (Cancelled)

20. (Previously presented) The distributed system of claim 15, further comprising a thermal insulator that encases the structure.

21-27. (Canceled)

28. (Previously presented) A circuit, comprising:  
a circuit board;  
a crystal component mounted on the circuit board; and  
means for increasing a thermal mass of the crystal component so as to reduce a thermal drift of the crystal component.

29. (Previously presented) The circuit of claim 28, wherein the means for increasing a thermal mass of the crystal component comprises a metal case adjacent to the crystal component.

30. (Previously presented) The circuit of claim 28, wherein the means for increasing a thermal mass of the crystal component comprises a ceramic case adjacent to the crystal component.

31. (Previously presented) The circuit of claim 28, further comprising a thermal insulator that encases the means for increasing the thermal mass of the crystal component.

32. (Previously presented) The circuit of claim 31, wherein the thermal insulator is styrofoam.